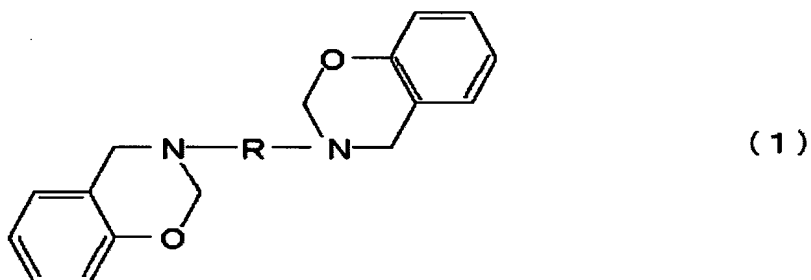


1. A thermosetting resin composition comprising an epoxy compound and a bifunctional dihydrobenzoxazine compound of the following general formula (1), wherein the equivalent ratio of the epoxy compound to the bifunctional dihydrobenzoxazine compound is 1/(0.1 to 20):



wherein R represents a linear alkylene group having at least 2 carbon atoms, or a branched alkylene group derived from it by substituting the hydrogen atom therein with an alkyl group, and the hydrogen atom of the benzene ring may be substituted with an alkyl group or an alkoxy group.

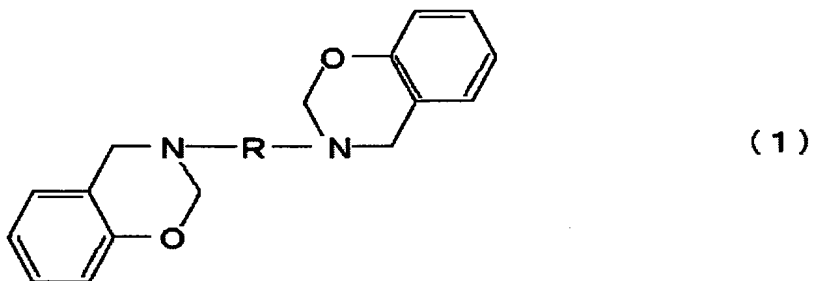
2. A thermosetting resin molding produced by thermally molding the thermosetting resin composition of claim 1.

3. The thermosetting resin molding as claimed in claim 2, which has a dielectric constant of at most 3.5 and a dielectric loss tangent of at most 0.015, at 23°C at 1 GHz.

4. The thermosetting resin molding as claimed in claim 2, which has a Young's modulus at 23°C from 0.5 to 5.5 GPa, and has an elongation at break at 23°C from 2.0 to 40%.

5. A thermosetting resin composition comprising an epoxy compound, a bifunctional dihydrobenzoxazine compound of the

following general formula (1) and a curing agent for epoxy compound, wherein the equivalent ratio of epoxy compound/bifunctional dihydrobenzoxazine compound/curing agent for epoxy compound is 1/(0.1 to 20)/(0 to 1.2):



wherein R represents a linear alkylene group having at least 2 carbon atoms, or a branched alkylene group derived from it by substituting the hydrogen atom therein with an alkyl group, and the hydrogen atom of the benzene ring may be substituted with an alkyl group or an alkoxy group.

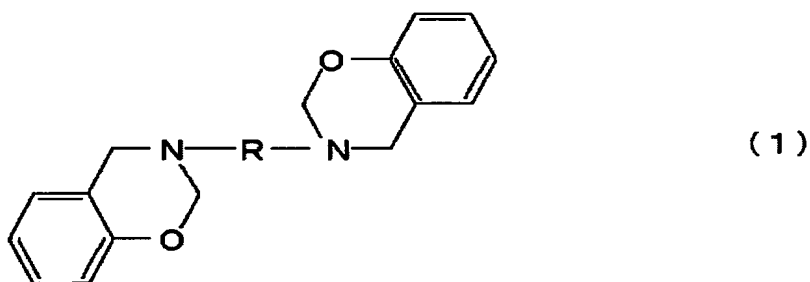
6. A thermosetting resin molding produced by thermally molding the thermosetting resin composition of claim 5.

7. The thermosetting resin molding as claimed in claim 6, which has a dielectric constant of at most 3.5 and a dielectric loss tangent of at most 0.015, at 23°C at 1 GHz.

8. The thermosetting resin molding as claimed in claim 6, which has a Young's modulus at 23°C from 0.5 to 5.5 GPa, and has an elongation at break at 23°C from 2.0 to 40%.

9. A thermosetting resin composition comprising an epoxy compound, a bifunctional dihydrobenzoxazine compound of the following general formula (1) and an inorganic filler, wherein

the equivalent ratio of the epoxy compound to the bifunctional dihydrobenzoxazine compound is 1/(0.1 to 20), and the amount of the inorganic filler is at most 400 parts by weight relative to 100 parts by weight of the total of the epoxy compound and the bifunctional dihydrobenzoxazine compound:



wherein R represents a linear alkylene group having at least 2 carbon atoms, or a branched alkylene group derived from it by substituting the hydrogen atom therein with an alkyl group, and the hydrogen atom of the benzene ring may be substituted with an alkyl group or an alkoxy group.

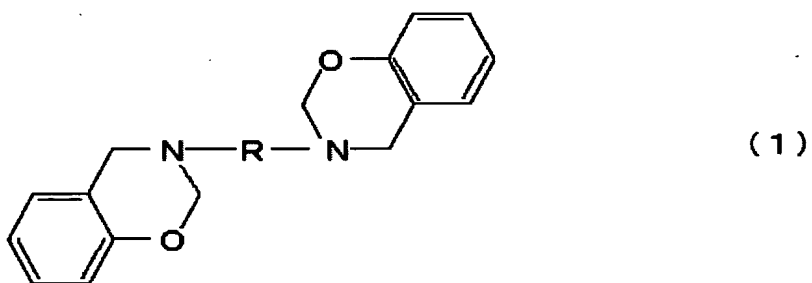
10. A thermosetting resin molding produced by thermally molding the thermosetting resin composition of claim 9.

11. The thermosetting resin molding as claimed in claim 10, which has a dielectric constant of at most 3.5 and a dielectric loss tangent of at most 0.015, at 23°C at 1 GHz.

12. The thermosetting resin molding as claimed in claim 10, which has a Young's modulus at 23°C from 0.5 to 5.5 GPa, and has an elongation at break at 23°C from 2.0 to 40%.

13. A thermosetting resin composition comprising an epoxy compound, a bifunctional dihydrobenzoxazine compound of

the following general formula (1), a curing agent for epoxy compound and an inorganic filler, wherein the equivalent ratio of epoxy compound/bifunctional dihydrobenzoxazine compound/curing agent for epoxy compound is 1/(0.1 to 20)/(0 to 1.2), and the amount of the inorganic filler is at most 400 parts by weight relative to 100 parts by weight of the total of the epoxy compound, the bifunctional dihydrobenzoxazine compound and the curing agent for epoxy resin:



wherein R represents a linear alkylene group having at least 2 carbon atoms, or a branched alkylene group derived from it by substituting the hydrogen atom therein with an alkyl group, and the hydrogen atom of the benzene ring may be substituted with an alkyl group or an alkoxy group.

14. A thermosetting resin molding produced by thermally molding the thermosetting resin composition of claim 13.

15. The thermosetting resin molding as claimed in claim 14, which has a dielectric constant of at most 3.5 and a dielectric loss tangent of at most 0.015, at 23°C at 1 GHz.

16. The thermosetting resin molding as claimed in claim 14, which has a Young's modulus at 23°C from 0.5 to 5.5 GPa,

and has an elongation at break at 23°C from 2.0 to 40%.